## Synchronous Buck Regulator 6 MHz, 1.2 A

### **FAN53602**

#### **DESCRIPTION**

The FAN53602 is a 6 MHz, step-down switching voltage regulator that delivers a fixed output from an input voltage supply of 2.3 V to 5.5 V. Using a proprietary architecture with synchronous rectification, the FAN53602 is capable of delivering a constant load of 1.2 A.

The regulator operates at a nominal fixed frequency of 6 MHz, which reduces the value of the external components to as low as 470 nH for the output inductor and  $4.7 \, \mu \text{F}$  for the output capacitor. In addition, the Pulse Width Modulation (PWM) modulator can be synchronized to an external frequency source.

At moderate and light loads, Pulse Frequency Modulation (PFM) is used to operate the device in Power–Save Mode with a typical quiescent current of 24  $\mu A$ . Even with such a low quiescent current, the part exhibits excellent transient response during large load swings. At higher loads, the system automatically switches to fixed–frequency control, operating at 6 MHz. In Shutdown Mode, the supply current drops below 1  $\mu A$ , reducing power consumption. For applications that require minimum ripple or fixed frequency, PFM Mode can be disabled using the MODE pin.

The FAN53602 is available in 6-bump, 0.4 mm pitch, Wafer-Level Chip-Scale Package (WLCSP).

#### **Features**

- 1.2 A Output Current Capability
- 24 μA Typical Quiescent Current
- 6 MHz Fixed-Frequency Operation
- Best-in-Class Load Transient Response
- Best-in-Class Efficiency
- 2.3 V to 5.5 V Input Voltage Range
- Low Ripple Light-Load PFM Mode
- Forced PWM and External Clock Synchronization
- Internal Soft-Start
- Input Under-Voltage Lockout (UVLO)
- Thermal Shutdown and Overload Protection
- 6-Bump WLCSP, 0.4 mm Pitch

#### **Application**

- 3G, 4G, WiFi<sup>®</sup>, WiMAX<sup>™</sup>, and WiBro<sup>™</sup> Data Cards
- Tablets
- DSC, DVC
- Netbooks



#### ON Semiconductor®

www.onsemi.com



WLCSP6 1.16x0.86x0.586 CASE 567QE

#### **MARKING DIAGRAM**



12 = Alphanumeric Device Marking

KK = Lot Run Code

X = Alphabetical Year CodeY = 2 Weeks Date CodeZ = Assembly Plant Code

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

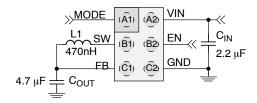


Figure 1. Typical Application

**Table 1. ORDERING INFORMATION** 

Part Number	Output Voltage	Package	Temperature Range	Packing Method <sup>†</sup>	Device Marking
FAN53602UC123X	1.233 V	WLCSP – 6, 0.4 mm Pitch	−40 to 85°C	3000 / Tape & Reel	TZ

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **PIN CONFIGURATION**



Figure 2. Bumps Facing Down

Figure 3. Bumps Facing Up

#### **Table 2. PIN DEFINITIONS**

Pin #	Name	Description	
A1	MODE	MODE. Logic 1 on this pin forces the IC to stay in PWM Mode. A logic 0 allows the IC to automatically switch to PFM during light loads. The regulator also synchronizes its switching frequency to four times the frequency provided on this pin. Do not leave this pin floating.	
B1	SW	Switching Node. Connect to output inductor.	
C1	FB	Feedback / VOUT. Connect to output voltage.	
C2	GND	Ground. Power and IC ground. All signals are referenced to this pin.	
B2	EN	Enable. The device is in Shutdown Mode when voltage to this pin is $< 0.4 \text{ V}$ and enabled when $> 1.2 \text{ V}$ . Do not leave this pin floating.	
A2	VIN	Input Voltage. Connect to input power source.	

#### **Table 3. ABSOLUTE MAXIMUM RATINGS**

Symbol		Parameter	Min.	Max.	Unit
V <sub>IN</sub>	Input Voltage		-0.3	7.0	V
$V_{SW}$	Voltage on SW Pin		-0.3	V <sub>IN</sub> + 0.3 (Note 1)	V
V <sub>CTRL</sub>	EN and Mode Pin Voltage	EN and Mode Pin Voltage		V <sub>IN</sub> + 0.3 (Note 1)	V
	Other Pins		-0.3	V <sub>IN</sub> + 0.3 (Note 1)	V
ESD	Electrostatic Discharge	Human Body Model per JESD22-A114		2.0	
	Protection Level	Charged Device Model per JESD22-C101		1.5	
TJ	Junction Temperature		-40	+150	°C
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
$T_L$	Lead Soldering Temperatu	ure, 10 Seconds		+260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **Table 4. THERMAL PROPERTIES**

Symbol	Parameter	Тур.	Unit
$\theta_{JAn}$	Junction-to-Ambient Thermal Resistance	125	°C/W

NOTE: Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards without vias in accordance to JEDEC standard JESD51. Special attention must be paid to not exceed junction temperature  $T_{J(max)}$  at a given ambient temperature  $T_A$ .

<sup>1.</sup> Lesser of 7 V or V<sub>IN</sub> + 0.3 V.

**Table 5. RECOMMENDED OPERATING CONDITIONS** 

Symbol	Parameter	Min.	Тур.	Max.	Unit
V <sub>CC</sub>	Supply Voltage Range	2.3		5.5	V
Гоит	Output Current	1200			mA
L	Inductor		470		nΗ
C <sub>IN</sub>	Input Capacitor		2.2		μF
C <sub>OUT</sub>	Output Capacitor	1.6	4.7	12.0	μΗ
T <sub>A</sub>	Operating Ambient Temperature	-40		+85	°C
$T_J$	Operating Junction Temperature	-40		+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

**Table 6. ELECTRICAL CHARACTERISTICS** ( Note 2) Minimum and Maximum Values are at  $V_{IN} = V_{EN} = 2.3 \text{ V}$  to 5.5 V,  $V_{MODE} = 0 \text{ V}$  (AUTO Mode),  $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ , circuit of Figure 1, unless otherwise noted. Typical values are at  $T_A = 25^{\circ}\text{C}$ ,  $V_{IN} = V_{EN} = 3.6 \text{ V}$ .

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
		Power Supplies	•	•	•	
ΙQ	Quiescent Current	No Load, Not Switching		24	50	μΑ
		PWM Mode		8		mA
I <sub>(SD)</sub>	Shutdown Supply Current	EN = GND, V <sub>IN</sub> = 3.6 V,		0.25	1.00	μΑ
$V_{UVLO}$	Under-Voltage Lockout Threshold	Rising VIN		2.15	2.27	V
V <sub>UVHYST</sub>	Under-Voltage Lockout Hysteresis			200		mV
	Logic In	puts: EN and MODE Pins				
V <sub>IH</sub>	Enable HIGH-Level Input Voltage		1.2			V
$V_{IL}$	Enable Low-Level Input Voltage				0.4	V
V <sub>LHYST</sub>	Logic Input Hysteresis Voltage			100		mV
I <sub>IN</sub>	Enable Input Leakage Current	Pin to VIN or GND		0.01	1.00	μΑ
	Switch	ing and Synchronization				
f <sub>SW</sub>	Switching Frequency (Note 3)	VIN = 3.6 V, T <sub>A</sub> = 25°C, PWM Mode, IOUT = 10 mA	5.4	6.0	6.6	MHz
f <sub>SYNC</sub>	MODE Synchronization Range (Note 3)	Square Wave at MODE Input	1.3	1.5	1.7	MHz
		Regulation	•			
Vo	Output Voltage Accuracy	VIN = 3.6 V, IOUT = 0 mA, PWM	1.202	1.233	1.264	V
		AUTO Mode, IOUT = 0 to 1.2 A	1.171	1.233	1.281	V
t <sub>SS</sub>	Soft-Start	VIN = 4.5 V, From EN Rising Edge to 95% VOUT		180	300	μs
		Output Driver	•		•	
R <sub>DS(on)</sub>	PMOS On Resistance	VIN = V <sub>GS</sub> = 3.6 V		175		mΩ
	NMOS On Resistance	VIN = V <sub>GS</sub> = 3.6 V		165		mΩ
I <sub>LIM(OL)</sub>	PMOS Peak Current Limit	VIN = 3.6 V, T <sub>A</sub> = 25°C	1.70	1.95	2.20	Α
$T_{TSD}$	Thermal Shutdown			150		°C
T <sub>HYS</sub>	Thermal Shutdown Hysteresis			15		°C

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>2.</sup> The Electrical Characteristics table reflects open-loop data. Refer to the Operation Description and Typical Characteristics Sections for closed-loop data.

<sup>3.</sup> Limited by the effect of t<sub>OFF</sub> minimum (see Operation Description section).

#### TYPICAL PERFORMANCE CHARACTERISTIC

Unless otherwise noted,  $V_{IN} = V_{EN} = 3.6 \text{ V}$ ,  $V_{MODE} = 0 \text{ V}$  (AUTO Mode),  $V_{OUT} = 1.233 \text{ V}$ , ,  $T_A = 25^{\circ}\text{C}$ 

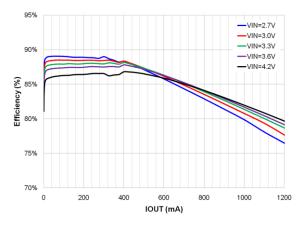


Figure 4. Efficiency vs. Load Current and Input Voltage

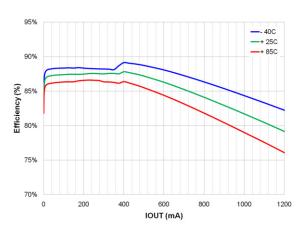


Figure 5. Efficiency vs. Load Current and Temperature

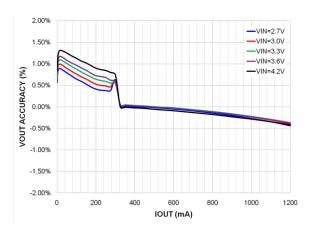


Figure 6. VOUT Accuracy vs. Load Current and Input Voltage

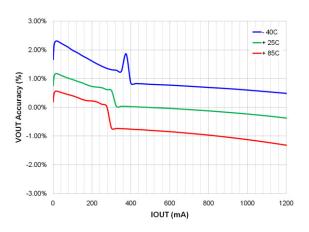


Figure 7. VOUT Accuracy vs. Load Current and Temperature

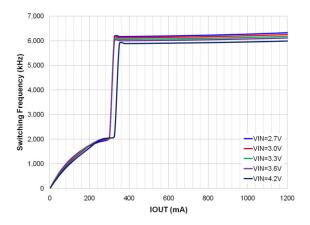


Figure 8. Switching Frequency vs. Load Current and Input Volatage

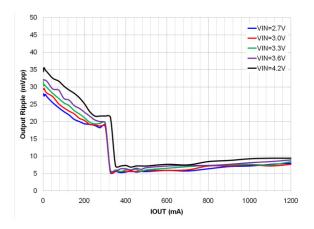


Figure 9. Output Ripple vs. Load Current and Input Voltage

#### TYPICAL PERFORMANCE CHARACTERISTIC (continued)

Unless otherwise noted,  $V_{IN} = V_{EN} = 3.6 \text{ V}$ ,  $V_{MODE} = 0 \text{ V}$  (AUTO Mode),  $V_{OUT} = 1.233 \text{ V}$ , ,  $T_A = 25^{\circ}C$ 

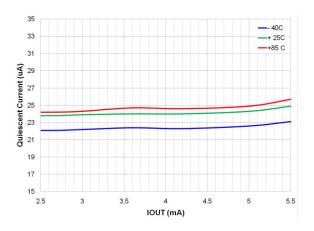


Figure 10. Quiescent Current vs. Input Voltage and Temperature

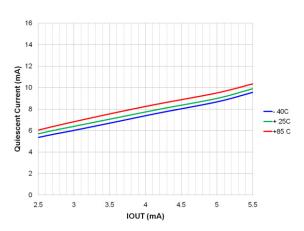


Figure 11. Quiescent Current vs. Input Volatage and Temperature, FPWM Mode

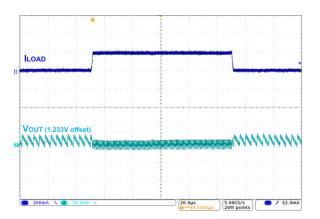


Figure 12. Load Transient, 10 mA ↔ 200 mA in 1 μs

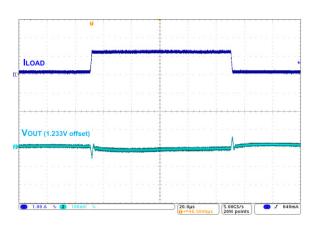


Figure 13. Load Transient, 150 mA ↔ 1200 mA in 1 μs

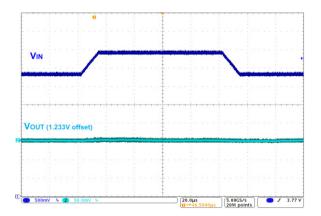


Figure 14. Line Transient, 3.3 V  $\leftrightarrow$  3.9 V in 10  $\mu s,$  1200 mA Load

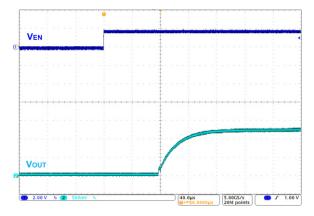


Figure 15. Startup, 800 mA Load

#### **OPERATION DESCRIPTION**

The FAN53602 is a 6 MHz, step-down switching voltage regulator that delivers a fixed output from an input voltage supply of 2.3 V to 5.5 V. Using a proprietary architecture with synchronous rectification, the FAN53602 is capable of delivering a constant 1.2 A load current.

The regulator operates at a nominal fixed frequency of 6 MHz, which reduces the value of the external components to as low as 470 nH for the output inductor and 4.7  $\mu F$  for the output capacitor. In addition, the PWM modulator can be synchronized to an external frequency source.

#### **Control Scheme**

The FAN53602 uses a proprietary, non-linear, fixed-frequency PWM modulator to deliver a fast load transient response, while maintaining a constant switching frequency over a wide range of operating conditions. The regulator performance is independent of the output capacitor ESR, allowing for the use of ceramic output capacitors. Although this type of operation normally results in a switching frequency that varies with input voltage and load current, an internal frequency loop holds the switching frequency constant over a large range of input voltages and load currents.

For very light loads, the FAN53602 operates in Discontinuous Current Mode (DCM) single-pulse PFM Mode, which produces low output ripple compared with other PFM architectures. Transition between PWM and PFM is seamless, allowing for a smooth transition between DCM and CCM.

Combined with exceptional transient response characteristics, the very low quiescent current of the controller maintains high efficiency; even at very light loads, while preserving fast transient response for applications requiring tight output regulation.

#### **Enable and Soft-Start**

When EN is LOW, all circuits are off and the IC draws ~250 nA of current. When EN is HIGH and VIN is above its UVLO threshold, the regulator begins a soft–start cycle. The output ramp during soft–start is a fixed slew rate of  $50 \text{ mV/}\mu\text{s}$  from VOUT = 0 to 1 V, then 12.5 mV/ $\mu$ s until the output reaches its setpoint. Regardless of the state of the MODE pin, PFM Mode is enabled to prevent current from being discharged from COUT if soft–start begins when COUT is charged.

The current-limit fault response protects the IC in the event of an over-current condition present during soft-start. As a result, the IC may fail to start if heavy load is applied during startup and/or if excessive COUT is used.

The current required to charge COUT during soft-start commonly referred to as "displacement current" is given as:

$$I_{DISP} = C_{OUT} \cdot \frac{dV}{dt}$$
 (eq. 1)

Where  $\frac{dV}{dt}$  refers to the soft–start slew rate.

To prevent shut down during soft-start, the following condition must be met:

$$I_{DISP} + I_{LOAD} < I_{MAX(DC)}$$
 (eq. 2)

Where  $I_{MAX(DC)}$  is the maximum load current the IC is guaranteed to support.

#### Startup into Large Cout

Multiple soft–start cycles are required for no–load startup if COUT is greater than 15  $\mu F$ . Large COUT requires light initial load to ensure the FAN53602 starts appropriately. The IC shuts down for 1.3 ms when IDISP exceeds ILIMIT for more than 200  $\mu s$  of current limit. The IC then begins a new soft–start cycle. Since COUT retains its charge when the IC is off, the IC reaches regulation after multiple soft–start attempts.

#### **MODE Pin**

Logic 1 on this pin forces the IC to stay in PWM Mode. A logic 0 allows the IC to automatically switch to PFM during light loads. If the MODE pin is toggled with a frequency between 1.3 MHz and 1.7 MHz, the converter synchronizes its switching frequency to four times the frequency on the MODE pin.

The MODE pin is internally buffered with a Schmitt trigger, which allows the MODE pin to be driven with slow rise and fall times. An asymmetric duty cycle for frequency synchronization is also permitted as long as the minimum time below  $V_{IL(MAX)}$  or above  $V_{IH(MAX)}$  is 100 ns.

#### **Current Limit, Fault Shutdown and Restart**

A heavy load or short circuit on the output causes the current in the inductor to increase until a maximum current threshold is reached in the high-side switch. Upon reaching this point, the high-side switch turns off, preventing high currents from causing damage. The regulator continues to limit the current cycle-by-cycle. After 16 cycles of current limit, the regulator triggers an over-current fault, causing the regulator to shut down for about 1.3 ms before attempting a restart.

If the fault is caused by short circuit, the soft–start circuit attempts to restart and produces an over–current fault after about 200  $\mu$ s, which results in a duty cycle of less than 15%, limiting power dissipation.

The closed-loop peak-current limit is not the same as the open-loop tested current limit, ILIM(OL), in the Electrical Characteristics table. This is primarily due to the effect of propagation delays of the IC current limit comparator.

#### Under-Voltage Lockout (UVLO)

When EN is HIGH, the under-voltage lockout keeps the part from operating until the input supply voltage rises high enough to properly operate. This ensures no misbehavior of the regulator during startup or shutdown.

#### Thermal Shutdown (TSD)

When the die temperature increases, due to a high load condition and/or a high ambient temperature; the output switching is disabled until the die temperature falls sufficiently. The junction temperature at which the thermal shutdown activates is nominally 150°C with a 15°C hysteresis.

#### Minimum Off-Time Effect on Switching Frequency

 $t_{\rm OFF(MIN)}$  is 40 ns. This imposes constraints on the maximum  $\frac{V_{\rm OUT}}{V_{\rm IN}}$  that the FAN53602 can provide or the maximum output voltage it can provide at low VIN while maintaining a fixed switching frequency in PWM Mode. When VIN is LOW, fixed switching is maintained as long as:

$$\frac{V_{\text{OUT}}}{V_{\text{IN}}} \le 1 - t_{\text{OFF(MIN)}} \cdot f_{\text{SW}} \approx 0.7$$

The switching frequency drops when the regulator cannot provide sufficient duty cycle at 6 MHz to maintain regulation.

The calculation for switching frequency is given by:

$$f_{SW} = min \left( \frac{1}{t_{SW(MAX)}}, 6 \text{ MHz} \right)$$
 (eq. 3)

Where:

$$t_{\text{SW(MAX)}} = 40 \text{ ns} \cdot \left(1 + \frac{V_{\text{OUT}} + I_{\text{OUT}} \cdot R_{\text{OFF}}}{V_{\text{IN}} - I_{\text{OUT}} \cdot R_{\text{ON}} - V_{\text{OUT}}}\right)$$
(eq. 4)

Where:

$$R_{OFF} = R_{DSON\_N} + DCR_L$$
  
 $R_{ON} = R_{DSON\_P} + DCR_L$ 

#### **APPLICATIONS INFORMATION**

#### Selecting the Inductor

The output inductor must meet both the required inductance and the energy-handling capability of the application. The inductor value affects average current limit, the PWM-to-PFM transition point, output voltage ripple, and efficiency.

The ripple current ( $\Delta I$ ) of the regulator is:

$$\Delta I \approx \frac{V_{OUT}}{V_{IN}} \cdot \left(\frac{V_{IN} - V_{OUT}}{L \cdot f_{SW}}\right)$$
 (eq. 5)

The maximum average load current,  $I_{MAX(LOAD)}$ , is related to the peak current limit,  $I_{LIM(PK)}$ , by the ripple current, given by:

$$I_{MAX(LOAD)} = I_{LIM(PK)} - \frac{\Delta I}{2}$$
 (eq. 6)

The transition between PFM and PWM operation is determined by the point at which the inductor valley current crosses zero. The regulator DC current when the inductor current crosses zero, I<sub>DCM</sub>, is:

$$I_{DCM} = \frac{\Delta I}{2}$$
 (eq. 7)

The FAN53602 is optimized for operation with  $L=470\,\text{nH}$ , but is stable with inductances up to  $1\,\mu\text{H}$  (nominal). The inductor should be rated to maintain at least 80% of its value at  $I_{LIM(PK)}$ .

Efficiency is affected by the inductor DCR and inductance value. Decreasing the inductor value for a given physical size typically decreases the DCR; but because  $\Delta I$  increases, the RMS current increases, as do the core and skin effect losses.

$$I_{RMS} = \sqrt{I_{OUT(DC)}^2 + \frac{\Delta I^2}{12}}$$
 (eq. 8)

The increased RMS current produces higher losses through the  $R_{DS(ON)}$  of the IC MOSFETs, as well as the inductor DCR.

Increasing the inductor value produces lower RMS currents, but degrades transient response. For a given physical inductor size, increased inductance usually results in an inductor with lower saturation current and higher DCR.

Table 7 shows the effects of inductance higher or lower than the recommended 1  $\mu$ H on regulator performance.

#### **Output Capacitor**

Table 8 suggests 0402 capacitors. 0603 capacitors may further improve performance in that the effective capacitance is higher. This improves transient response and output ripple.

Increasing  $C_{OUT}$  has no effect on loop stability and can therefore be increased to reduce output voltage ripple or to improve transient response. Output voltage ripple,  $\Delta V_{OUT}$ , is:

$$\Delta V_{\text{OUT}} = \Delta I_{\text{L}} \left[ \frac{f_{\text{SW}} \cdot C_{\text{OUT}} \cdot \text{ESR}^2}{2 \cdot D \cdot (1 - D)} + \frac{1}{8 \cdot f_{\text{SW}} \cdot C_{\text{OUT}}} \right]$$
(eq. 9)

#### **Input Capacitor**

The 2.2  $\mu$ F ceramic input capacitor should be placed as close as possible between the VIN pin and GND to minimize the parasitic inductance. If a long wire is used to bring power to the IC, additional "bulk" capacitance (electrolytic or tantalum) should be placed between  $C_{IN}$  and the power source lead to reduce the ringing that can occur between the inductance of the power source leads and  $C_{IN}$ .

The effective capacitance value decreases as VIN increases due to DC bias effects.

## Table 7. EFFECTS OF CHANGES IN INDUCTOR VALUE (FROM 470 nH RECOMMENDED VALUE) ON REGULATOR PERFORMANCE

Inductor Value	I <sub>MAX(LOAD)</sub>	$\Delta V_{OUT}$	Transient Response
Increase	Increase	Decrease	Degraded
Decrease	Decrease	Increase	Improved

#### Table 8. RECOMMENDED PASSIVE COMPONENTS AND THEIR VARIATION DUE TO DC BIAS

Component	Description	Vendor	Min.	Тур.	Max.
L1	$0.47~\mu\text{H}/5.3~\text{A}/26~\text{m}\Omega$ $2.0~\text{x}$ 1.6 1.0 mm	Murata DFE201610E-R47M		470 nH	
C <sub>IN</sub>	2.2 μF, 6.3 V, X5R, 0402	Murata or Equivalent GRM155R60J225ME15 GRM188R60J225KE19D	1.0 μF	2.2 μF	
C <sub>OUT</sub>	4.7 μF, X5R, 0402	Murata or Equivalent GRM155R60G475M GRM155R60E475ME760	1.6 μF	4.7 μF	

#### **PCB LAYOUT GUIDELINES**

There are only three external components: the inductor and the input and output capacitors. For any buck switcher IC, including the FAN53602, it is important to place a low–ESR input capacitor very close to the IC, as shown in Figure 16. The input capacitor ensures good input decoupling, which helps reduce noise appearing at the output terminals and ensures that the control sections

of the IC do not behave erratically due to excessive noise. This reduces switching cycle jitter and ensures good overall performance. It is important to place the common GND of CIN and COUT as close as possible to the C2 terminal. There is some flexibility in moving the inductor further away from the IC; in that case, VOUT should be considered at the COUT terminal.

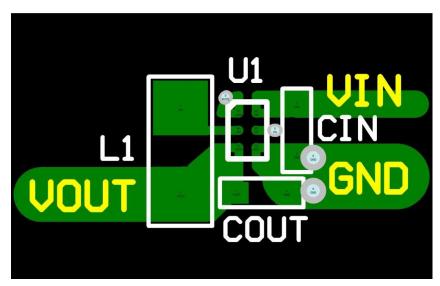


Figure 16. PCB Layout Guidance

#### PRODUCT-SPECIFIC DIMENSIONS

D	E	Х	Υ
$1.160 \pm 0.030$	$0.860 \pm 0.030$	0.230	0.180

Wi-Fi is a registered trademark of the Wi-Fi Alliance.

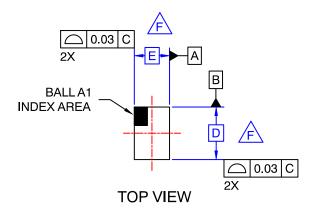
WiMAX is a trademark of WiMAX Forum.

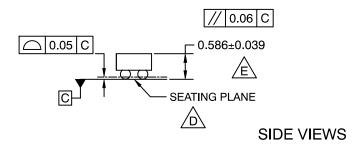
WiBro is a trademark and brand of Telecommunications Technology Association.

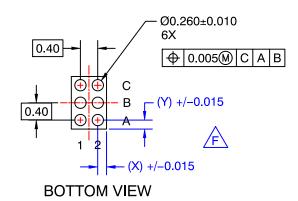
All brand names and product names appearing in this document are registered trademarks or trademarks of their respective holders.

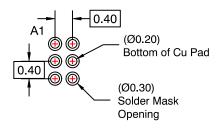
#### WLCSP6 1.16x0.86x0.586 CASE 567QE ISSUE O

**DATE 31 OCT 2016** 

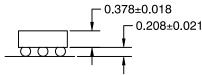








# RECOMMENDED LAND PATTERN (NSMD PAD TYPE)



#### NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASMEY14.5M, 2009.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- PACKAGE TYPICAL HEIGHT IS 586 MICRONS ±39 MICRONS (547–625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y, SEE PRODUCT DATASHEET.

DOCUMENT NUMBER:	98AON13324G	accessed directly from the Document I	
STATUS:	ON SEMICONDUCTOR STANDARD		. ,
NEW STANDARD:		"CONTROLLED COPY" in red.	
DESCRIPTION:	WLCSP6 1.16x0.86x0.586		PAGE 1 OF 2



<b>DOCUMENT</b>	NUMBER:
98AON13324	ŀG

PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION FROM FAIRCHILD UC006AC TO ON SEMICONDUCTOR. REQ. BY F. ESTRADA.	31 OCT 2016
·		

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. arising out of the application to use of any product or circuit, and specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death. associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

© Semiconductor Components Industries, LLC, 2016 Case Outline Number: October, 2016 - Rev. O 567QE

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="https://www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative